

3.2x1.25 x1.1mm Reverse Mount Chip LED

OSXX1205C1N

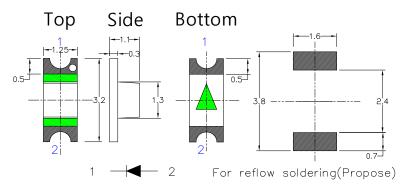
■Features

- · Single chip LED
- Super high brightness of reverse mount LED
- Compact package outline
 (L x W x T) of 3.2mm x 1.25mm x 1.1mm
- · Compatible to IR reflow soldering.
- · Water Clear Type

■Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

■Outline Dimension



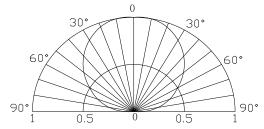
Unit: mm Tolerance: ±0.20mm unless otherwise noted

■Absolute Maximum Rating

(Ta=25°C)

Item	Cross la a l	Va	Unit	
Item	Symbol	W5/M5/B5/G5	G8/Y5//O5/R5	Onit
DC Forward Current	I_{F}	20	20	mA
Pulse Forward Current#	I_{FP}	100	100	mA
Reverse Voltage	V_R	5	5	V
Power Dissipation	P_{D}	68	48	mW
Operating Temperature	Topr	-40 ~	$^{\circ}\mathbb{C}$	
Storage Temperature	Tstg	-40~	$^{\circ}\mathbb{C}$	
Lead Soldering Temperature	Tsol	260°C	-	

■Directivity



#Pulse width Max 0.1ms, Duty ratio max 1/10

■Electrical -Optical Characteristics

(Ta=25°C)

		$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)		2θ1/2(deg)					
Part Number	Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	
			I _F =10mA		V _R =5V	I _F =10mA								
OSW51205C1N	White	W5		-	2.8	3.4	10	250	350	-	8000-18000K		00K	120
OSM51205C1N	Warm White	M5		-	2.8	3.4	10	250	350	-	2700-3300K		120	
OSB51205C1N	Blue	В5		-	2.8	3.4	10	60	80	-	460	465	475	120
OSG51205C1N	True Green	G5		-	2.8	3.4	10	300	400	-	515	525	530	120
OSG81205C1N	Yellow Green	G8		-	1.8	2.4	10	15	20	-	565	570	575	120
OSY51205C1N	Yellow	Y5		-	1.8	2.4	10	60	80	-	585	590	595	120
OSO51205C1N	Orange	O5		-	1.8	2.4	10	60	80	-	600	605	610	120
OSR51205C1N	Red	R5		1	1.8	2.4	10	60	80	-	615	625	630	120

^{*1} Tolerance of measurements of chromaticity coordinate is ±10%

CNAS (AF) ISO 9001: 2008







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^{*2} Tolerance of measurements of dominant wavelength is +1nm

^{*3} Tolerance of measurements of luminous intensity is ±15%

^{*4} Tolerance of measurements of forward voltage is±0.1V



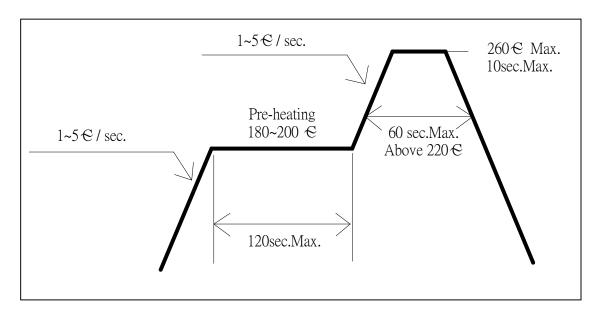
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■ Soldering Conditions

	Reflow Soldering	Hand Soldering				
Pre-Heat	180 ~ 200°C					
Pre-Heat Time	120 sec. Max.					
Peak temperature	260°C Max.	Temperature	350°C Max.			
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.			
Condition	Refer to Temperature-profile		(one time only)			

• Reflow Soldering Condition(Lead-free Solder)



- *Recommended soldering conditions vary according to the type of LED
- *Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- *A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

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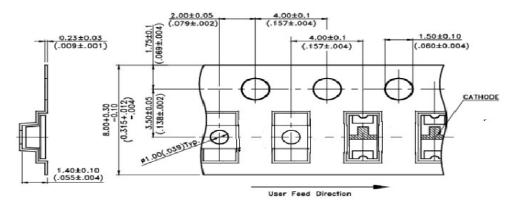


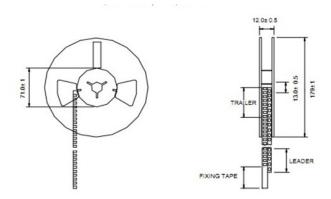
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■Reel & Tape Dimensions

- 1. Quantity:3000pcs/Reel
- 2. Note: The tolerances unless mentioned is ± 0.1 mm, Unit:mm





■ Cautions

- 1. After open the package, the LED´s floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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